ROLL NO.	

Code: AE04 **Subject: MATERIALS AND PROCESSES**

AMIETE - ET (OLD SCHEME)

OCTOBER 2012 Time: 3 Hours Max. Marks: 100

PLEASE WRITE YOUR ROLL NO. AT THE SPACE PROVIDED ON EACH PAGE IMMEDIATELY AFTER RECEIVING THE QUESTION PAPER.

NOTE: There are 9 Questions in all.

• Question 1 is compulsory and carries 20 marks. Answer to Q.1 must be written

Q.1	Cł	noose the correct or the be	st alternative in the following:	2 × 10)
	a.		plane in a unit cell intersects x, y, z respectively at points whose ances from origin are 1/3, 1/2 and 1/1 units. Its miller indices are	
		(A) (6 3 2) (C) (1 1 1)	(B) (3 2 1) (D) (1/3) (1/2) (1/1)	
	b.	Fick's first law of diffusion	n is applicable under	
		(A) Steady state condition(B) Non-steady state cond(C) Steady as well as non-(D) None of the above	itions	
	c.	The maximum number of system, at equilibrium is	of phases that can coexist in a single component	t
		(A) 5 (C) 3	(B) 7 (D) 2	
	d.	Which one of the follow dipoles?	ving material does not have permanent magnetic	
		(A) Ferromagnetic(C) Paramagnetic	(B) Antiferromagnetic(D) Diamagnetic	

e. Which one is the wrong anode-cathode combination?

(C) Iron-Tin (D) Nickel-Titanium

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	f.	The property of a material by which	it can be drawn into wires is known as	
		(A) Softness(C) Ductility	(B) Malleability(D) Tempering	
	g.	In order to increase the mechanical should go for	strength of an aluminium conductor, one	
		(A) Doping(C) Heat treatment	(B) cold working(D) steel reinforcement	
	h.	h. Magnetic susceptibility has the dimensions of		
		(A) Wb-m (C) Wb/m ²	(B) dimensionless(D) Amp/m	
	i.	For a tunnel diode a decrease in current causes		
		(A) Voltage constancy(C) Increase in voltage	(B) decrease in voltage(D) none of the above	
	j.	Manganin is an alloy of		
		(A) Manganese, Chromium, nickel(C) Copper, manganese, nickel	(B) Manganese, aluminium, nickel(D) none of the above	
		Answer any FIVE Questions ou Each question carrie		
Q.2	a.	Bonding in the intermetallic compound Ni ₃ Al is predominantly metallic. Explain why there will be little, if any, ionic bonding component. The electronegativity of nickel is about 1.8. (4) How many electrons are present in the 3d energy level of an element having a valence of 2 with an atomic number of 27? (4)		
	b.			
	c.	BCC lithium has a lattice parameter of 3.5089×10^{-8} cm and contains one vacancy per 200 unit cells. Calculate the number of vacancies per Cubic centimetre and the density of Li. (8)		
Q.3	a.	Explain Gibbs phase rule and what reaction is non-variant.	does it indicate? Show that eutectoid (8)	
	b.	b. The diffusion coefficient for Cr^{+3} in Cr_2O_3 is 6×10^{-15} cm ² /s at 727°C and is 1×10^{-9} cm ² /s at 1400°C. Calculate the activation energy and the constant D_o . (8		

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Q.4	a.	Find the conductivity of copper at 300 K, if the collision time for electron scattering in copper at 300 K is 2×10^{-14} sec. Given that density of copper= 8960 kg/m^3 , atomic weight of copper = 63.54 amu and mass of an electron = 9.1×10^{-31} kg.	=
	b.	Explain the effect of doping on the electrical conductivity of a semiconductor by giving a suitable example. The electrical conductivity of a semiconductor increases significantly on doping. Let us consider Ge at room temperature (=300 K). Given that electron mobility (μ_e) and hole mobility (μ_p) are 0.38 and 0.18 respectively.	f t
0.5		•	
Q.5	a.	State and explain Hall effect. What are its applications?	(8)
	b.	Define: (i) polarizability. (ii) dipole relaxation. (iii) loss angle. (iv) dielectric breakdown.	(8)
Q.6	a.	What is mica? Write the chemical composition of two types of mica with its properties and uses.	(8)
	b.	Write the chemical composition of constantan, German silver, manganin and nichrome along with their applications	, (8)
Q.7	a.	Describe the phenomenon of magnetic hysteresis and magnetization curve in a magnetic material. Also explain coercivity.	e (8)
	b.	Explain why ferromagnetic materials can be permanently magnetized whereas paramagnetic ones cannot.	l (8)
Q.8	a.	Explain the process of fabrication of integrated circuits.	(8)
	b.	What is extrusion? Explain hot and cold extrusion.	(8)
Q.9	W	rite short notes on any <u>TWO</u>	
		(i) Full annealing	

 (8×2)

(ii) Hardening and tempering (iii) BURGER VECTOR